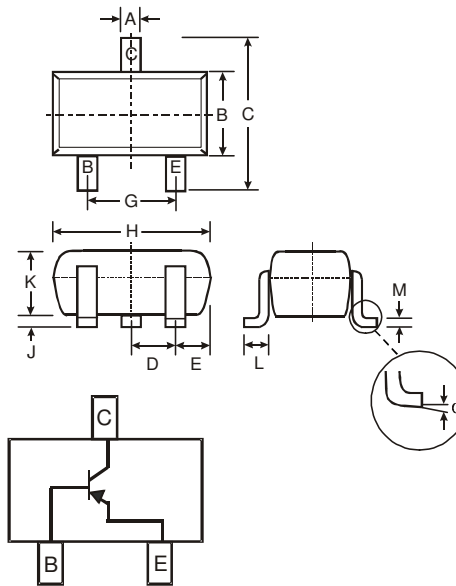


**Features**

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (MMSTA05/MMSTA06)
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- **Lead Free/RoHS Compliant (Note 2)**
- **"Green" Device (Note 3 and 4)**

**Mechanical Data**

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- MMSTA55 Marking K2H, K2G (See Page 3)
- MMSTA56 Marking K2G (See Page 3)
- Ordering & Date Code Information: See Page 3
- Weight: 0.006 grams (approximate)



SOT-323		
Dim	Min	Max
A	0.25	0.40
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
E	0.30	0.40
G	1.20	1.40
H	1.80	2.20
J	0.0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.18
$\alpha$	0°	8°
All Dimensions in mm		

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	MMSTA55	MMSTA56	Unit
Collector-Base Voltage	$V_{CB0}$	-60	-80	V
Collector-Emitter Voltage	$V_{CEO}$	-60	-80	V
Emitter-Base Voltage	$V_{EBO}$	-4.0		V
Collector Current - Continuous (Note 1)	$I_C$	-500		mA
Power Dissipation (Note 1)	$P_d$	200		mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	625		$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150		$^\circ\text{C}$

- Notes:
1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. No purposefully added lead.
  3. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  4. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
<b>OFF CHARACTERISTICS (Note 5)</b>						
Collector-Base Breakdown Voltage	MMSTA55 MMSTA56	V <sub>(BR)CBO</sub>	-60 -80	—	V	I <sub>C</sub> = -100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	MMSTA55 MMSTA56	V <sub>(BR)CEO</sub>	-60 -80	—	V	I <sub>C</sub> = -1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage		V <sub>(BR)EBO</sub>	-4.0	—	V	I <sub>E</sub> = -100μA, I <sub>C</sub> = 0
Collector Cutoff Current	MMSTA55 MMSTA56	I <sub>CBO</sub>	—	-100	nA	V <sub>CB</sub> = -60V, I <sub>E</sub> = 0 V <sub>CB</sub> = -80V, I <sub>E</sub> = 0
Collector Cutoff Current	MMSTA55 MMSTA56	I <sub>CEX</sub>	—	-100	nA	V <sub>CE</sub> = -60V, I <sub>BO</sub> = 0V V <sub>CE</sub> = -80V, I <sub>BO</sub> = 0V
<b>ON CHARACTERISTICS (Note 5)</b>						
DC Current Gain		h <sub>FE</sub>	100	—	—	I <sub>C</sub> = -10mA, V <sub>CE</sub> = -1.0V I <sub>C</sub> = -100mA, V <sub>CE</sub> = -1.0V
Collector-Emitter Saturation Voltage		V <sub>CE(SAT)</sub>	—	-0.25	V	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Base-Emitter Saturation Voltage		V <sub>BE(SAT)</sub>	—	-1.2	V	I <sub>C</sub> = -100mA, V <sub>CE</sub> = -1.0V
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Current Gain-Bandwidth Product		f <sub>T</sub>	50	—	MHz	V <sub>CE</sub> = -1.0V, I <sub>C</sub> = -100mA, f = 100MHz

Notes: 5. Short duration pulse test used to minimize self-heating effect.

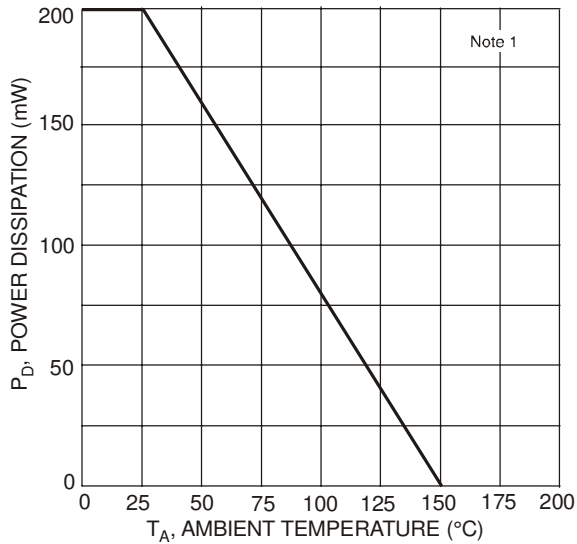


Fig. 1, Max Power Dissipation vs. Ambient Temperature

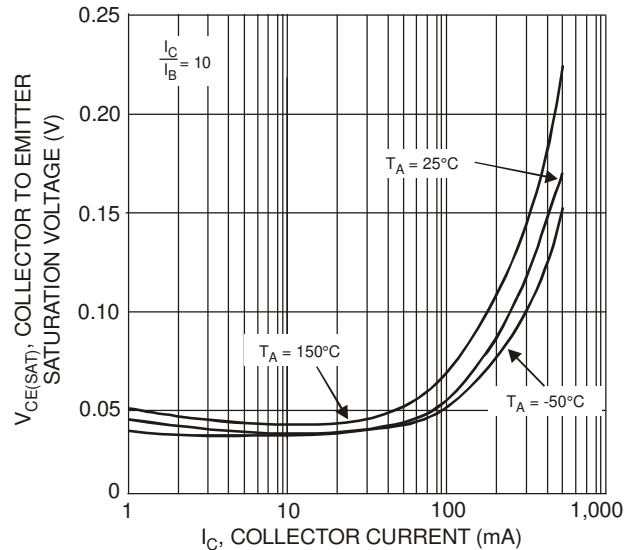


Fig. 2, Collector Emitter Saturation Voltage vs. Collector Current

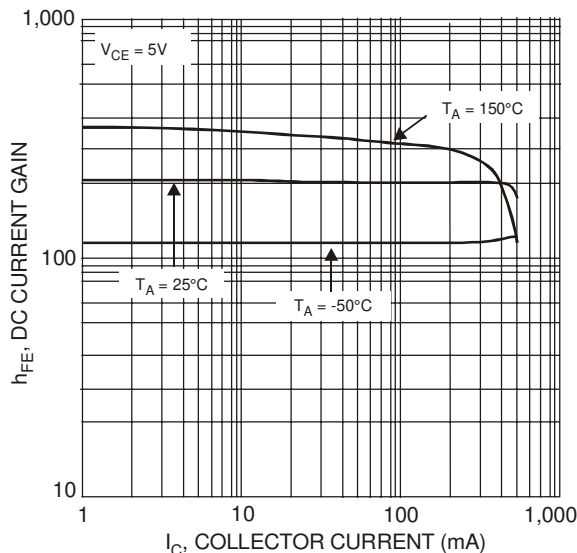


Fig. 3, DC Current Gain vs. Collector Current

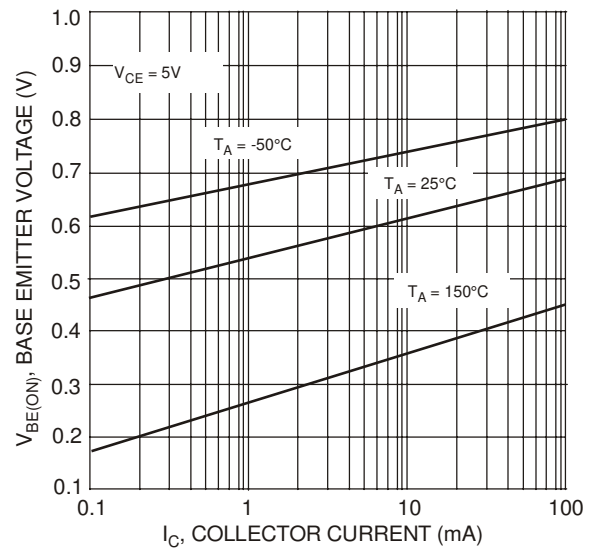


Fig. 4 Base Emitter Voltage vs. Collector Current

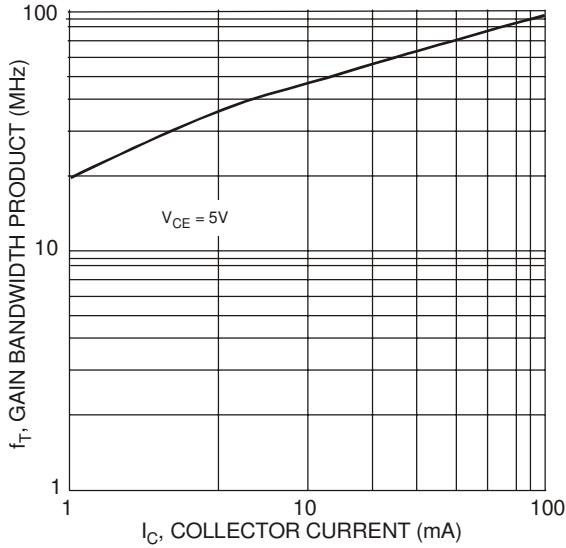


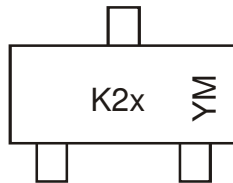
Fig. 5 Gain Bandwidth Product vs. Collector Current

## Ordering Information (Notes 4 and 6)

Device	Packaging	Shipping
MMSTA55-7-F	SOT-323	3000/Tape & Reel
MMSTA56-7-F	SOT-323	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



K2x = Product Type Marking Code, e.g. K2H = MMSTA55  
 YM = Date Code Marking  
 Y = Year ex: N = 2002  
 M = Month ex: 9 = September

### Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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